MA4SD10

Silicon epitaxial planar type

For super-high-speed switching circuits

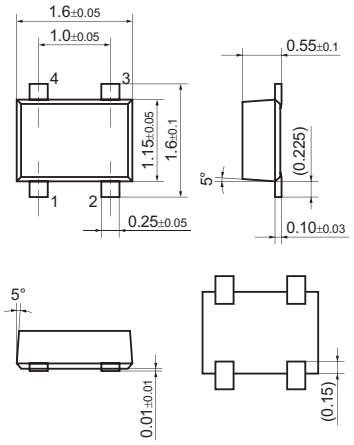
■ Features

- Two isolated elements are contained in one package, allowing high-density mounting
- Low forward voltage V_F

■ Absolute Maximum Ratings $T_a = 25°C$

Parameter		Symbol	Rating	Unit
Reverse voltage		V_R	20	V
Repetitive peak reverse voltage		V_{RRM}	20	V
Forward current (Average)	Single	$I_{F(AV)}$	200	mA
	Double		150	
Peak forward current	Single	I_{FM}	300	mA
	Double		225	
Junction temperature		T_j	125	°C
Storage temperature		T_{stg}	–55 to +125	°C

Unit: mm

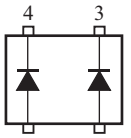


1: Anode 1
2: Anode 2
3: Cathode 2
4: Cathode 1

SSMini4-F1 Package

Marking Symbol: M2A

Internal Connection



■ Electrical Characteristics $T_a = 25°C \pm 3°C$

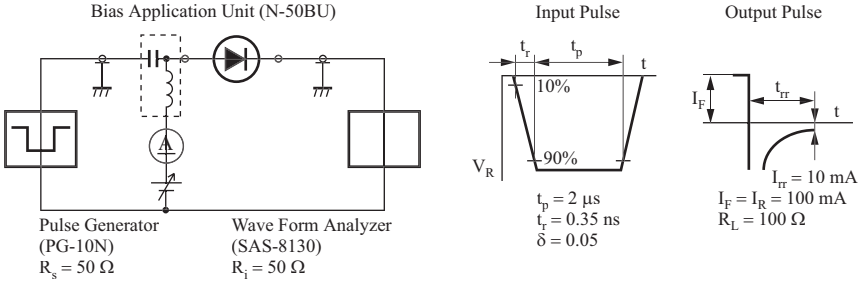
Parameter	Symbol	Conditions	Min	Typ	Max	Unit
Forward voltage	V_{F1}	I_F = 5 mA			0.27	V
	V_{F2}	I_F = 100 mA			0.40	
	V_{F3}	I_F = 200 mA			0.47	
Reverse current	I_R	V_R = 10 V			20	μA
Terminal capacitance	C_t	V_R = 0 V, f = 1 MHz		25		pF
Reverse recovery time *	t_{rr}	$I_F = I_R$ = 100 mA, I_{rr} = 10 mA R_L = 100 Ω		3		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

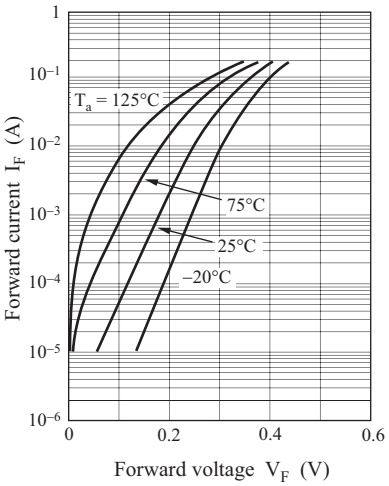
2. Absolute frequency of input and output is 250 MHz

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

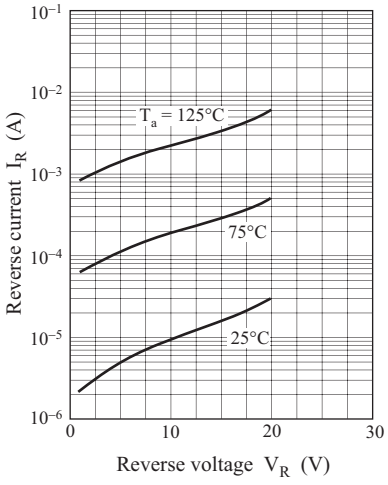
3. *: t_{rr} measurement circuit



I_F — V_F


1
10−1
10−2
10−3
10−4
10−5
10−6
Forward current IF (A)
Ta = 125°C
75°C
25°C
−20°C
0
0.2
0.4
0.6
Forward voltage VF (V)

I_R — V_R


10−1
10−2
10−3
10−4
10−5
10−6
Reverse current IR (A)
Ta = 125°C
75°C
25°C
0
10
20
30
Reverse voltage VR (V)

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